

Amendments to the Claims

This listing of the Claims will replace all prior versions and listings of the claims in this patent application.

Listing of the Claims

1-14. (canceled)

15. (currently amended) A method for fabricating a semiconductor wafer with a patterned contact point comprising gold, comprising:

ion milling said patterned contact point for cleaning said patterned contact point.

Claim 16 (canceled)

17. (currently amended) The method of claim 15, wherein said ion milling said patterned contact point comprises using argon.

Claims 18-26. (canceled)

27. (currently amended) A method for fabricating a semiconductor wafer, comprising:

depositing a patterned metal bump on a topmost patterned circuit layer of said semiconductor wafer, wherein said patterned metal bump has a substantially flat top surface; and

ion milling said patterned metal bump for cleaning said metal bump.

Claims 28 and 29. (canceled)

30. (currently amended) The method of claim 27, wherein said ion milling said patterned metal bump comprises using argon.

Claims 31-34. (canceled)